

PCN # 2098

DATE: October 30, 2020

EXPECTED PCN SHIP DATE: October 30, 2020



Quality Assurance
160 Rio Robles
San Jose, CA 95134

www.maximintegrated.com

PROCESS CHANGE NOTICE

PRODUCT CHANGE NOTICE

MAXIM INTEGRATED HEREBY ISSUES NOTIFICATION OF CHANGE
THAT MAY AFFECT THE FOLLOWING CATEGORIES:

<input type="checkbox"/> DESIGN	<input type="checkbox"/> WAFER FAB	<input checked="" type="checkbox"/> ASSEMBLY	<input type="checkbox"/> TEST	<input type="checkbox"/> ELEC/MECH SPECS
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AFFECTED PRODUCT:

Ordering P/N: (See PN listing XLS in PCN ZIP file)
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CHANGE FROM: - For Maxim product DS28E17Q+ The current Assembly Vendor UTAC DONGGUAN LTD/HONG KONG (UDG)	CHANGE TO: - Additional Assembler UTAC THAI LIMITED/Thailand (UTL)
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JUSTIFICATION: - UTL is being added as a second assembler to ensure supply continuity for our customers A qualification report is attached (reference 2098_R050168FQR) There are no regulatory compliance changes to the material content of the device There are no changes to form/fit/function at new assembler for the device

TRACEABILITY: Maxim Integrated maintains full traceability by device marking, packaging labels and shipment documents.
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Maxim Integrated's Change Notification System is designed to keep our customer base apprised of major product, manufacturing, or facility improvements.

Nasser Ali Chaouche

Nasser AliChaouche / PCN Coordinator

For further information, please contact either of the people listed below.

Contact your local Maxim Integrated Company Representative or Nasser AliChaouche, PCN Coordinator
408-601-5660 / pcn.coordinator@maximintegrated.com

Qualification
 Evaluation

MAXIM RELIABILITY QUALIFICATION REPORT

Report#: R050168FQR
Date: 3/24/06

PURPOSE

Qualify assembler NSEB Thailand (UTL) to build TQFN-EP, 0.5mm-pitch lead-free package with 6X6mm and 7X7mm body size

SUMMARY

All qualification lots assembled at NSEB have passed Maxim reliability requirements as well as moisture soak level 1 (MSL 1) testing per JEDEC J-STD-020C and solder reflow at 260°C peak temperature (Tp). Therefore, assembler NSEB is qualified to build 6X6 and 7X7 TQFN exposed paddle lead-free package.

TEST RESULTS/ LOT INFORMATION:

TEST	REL#: R050168A	REL#: R050168B	REL#: R050168C
	DEVICE: MAX1781ETM+	DEVICE: MAX1781ETM+	DEVICE: MAX1781ETM+
	DIE: UC03Y-1Z	DIE: UC03Y-1Z	DIE: UC03Y-1Z
	LOT#: SML1IA302Q1	LOT#: SML1IA302Q2	LOT#: SML1IA302Q3
	D/C: 0531	D/C: 0531	D/C: 0531
LIFE TEST	1000 HRS – 0/45	1000 HRS – 0/45	1000 HRS – 0/45
CONVECTION REFLOW *1	0/150	0/150	0/150
PRESSURE POT	168 HRS - 0/77	168 HRS - 0/77	168 HRS - 0/77
TEMP CYCLE *2	1000X - 0/77	1000X - 0/77	1000X - 0/77
HIGH TEMP STORAGE	1000 HRS – 0/77	1000 HRS - 0/77	1000 HRS - 0/77
HAST *2	100HRS – 0/45	100HRS – 0/45	100HRS – 0/45
WIRE BOND PULL	0/200 wires	0/200 wires	0/200 wires
SOLDER SHOCK	0/15	0/15	0/15
RESIST SOLDER HEAT	0/15	0/15	0/15
SOLDERABILITY	0/15	0/15	0/15

Stress Test

Test Condition

Life Test	135°C, 1000 hours
Convection Solder Reflow *1	260°C Tp, 3X
Pressure Pot	121°C/15 psig, 168 hours
Temperature Cycle *2	-65°C to +150°C, 1000 cycles
High Temperature Storage	150°C, 1000 hours
HAST *2	130°C/85% R.H., 100 hours
Wire Bond Pull	5 grams minimum
Solder Shock	260°C, 10 seconds
Resistance to Soldering Heat	300°C, 10 seconds
Solderability	8 hours steam aging

Note: *1. MSL 1 (168hrs of 85°C/85% R.H. soak) is preconditioning.
*2. Convection solder reflow at 260°C Tp is preconditioning for this test.

Affected product numbers

DS28E17Q+

DS28E17Q+T